



PIN FUNCTIONS		
CS	Chip Select	<b>ORG</b> Memory Array Organization Selection Input. When the ORG pin is connected to +5 V the 64 x 16 organization is selected. When it is connected to ground the 128 x 8 organization is selected. If the ORG pin is left unconnected, then an internal pull-up device will select the 64 x 16 organization.
SK	Clock Input	
DI	Serial Data Input	
DO	Serial Data Output	
V <sub>CC</sub>	+5 V Power Supply	
NC	Non Connection	
GND	Ground	

			INSTRUCTION SET				Comments
Instruction	Start Bit	Opcode	Address		Data		
			128 x 8	64 x 16	128 x 8	64 x 16	
READ	1	1 0	A <sub>6</sub> -A <sub>0</sub>	A <sub>5</sub> -A <sub>0</sub>			Read Address A <sub>N</sub> -A <sub>0</sub>
ERASE	1	1 1	A <sub>6</sub> -A <sub>0</sub>	A <sub>5</sub> -A <sub>0</sub>			ERASE Address A <sub>N</sub> -A <sub>0</sub>
WRITE	1	0 1	A <sub>6</sub> -A <sub>0</sub>	A <sub>5</sub> -A <sub>0</sub>	D <sub>7</sub> -D <sub>0</sub>	D <sub>15</sub> -D <sub>0</sub>	WRITE Address A <sub>N</sub> -A <sub>0</sub>
EWEN	1	0 0	11XXXXX	11XXXX			Program Enable
EWDS	1	0 0	00XXXXX	00XXXX			Program Disable
ERAL	1	0 0	10XXXXX	10XXXX			Erase All Addresses
WRAL	1	0 0	01XXXXX	01XXXX	D <sub>7</sub> -D <sub>0</sub>	D <sub>15</sub> -D <sub>0</sub>	Program All Addresses

**Power-On Data Protection Circuitry:** During power-up all modes of operation are inhibited until V<sub>CC</sub> has reached a level of between 2.8 and 3.5 volts. During power-down the source data protection circuitry acts to inhibit all modes when V<sub>CC</sub> has fallen below the voltage range of 2.8 to 3.5 volts.

### ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Value	Unit
Supply Voltage	V <sub>CC</sub>	T <sub>a</sub> = 25 °C	-0.3 ~ 7	V
Input Voltage	V <sub>I</sub>		-0.3 ~ V <sub>CC</sub> + 0.3	V
Output Voltage	V <sub>o</sub>		-0.3 ~ V <sub>CC</sub> + 0.3	V
Storage Temperature	T <sub>STG</sub>		-55 ~ + 150	°C

Note: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as recommended. Exposure to ABSOLUTE MAXIMUM RATINGS for extended periods may affect device reliability.

### RECOMMENDED OPERATING RANGE

Parameter	Symbol	Range	Unit
Supply Voltage	V <sub>CC</sub>	5 ± 10%	V
Temperature Range	T <sub>a</sub>	0 ~ 70	°C
Data Hold Temperature	T <sub>a</sub>	0 ~ 70	°C

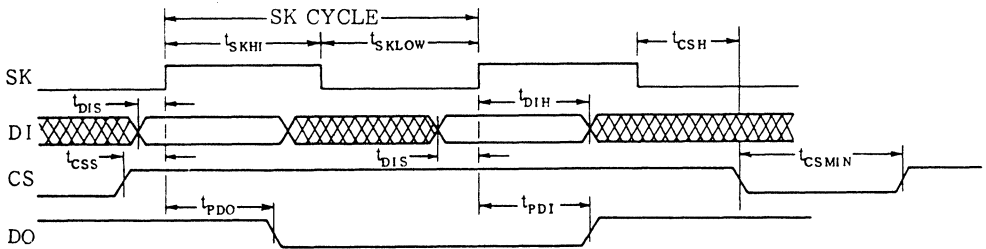
### DC CHARACTERISTICS

(V<sub>CC</sub> = 4.5V to 5.5V, T<sub>a</sub> = -0 ~ 70°C, unless otherwise specified.)

Parameter	Symbol	Condition	MIN	MAX	Unit
Supply Voltage	V <sub>CC</sub>		4.5	5.5	V
Power Supply Current	I <sub>CC1</sub>	V <sub>CC</sub> = 5.5 V CS = 1		3	mA
	I <sub>CC2</sub>	V <sub>CC</sub> = 5.5 V CS = 0 DI = 0 or V <sub>CC</sub>		100	μA
“L” Input Voltage	V <sub>IL</sub>		-0.1	0.8	V
“H” Input Voltage	V <sub>IH</sub>		2.0	V <sub>CC</sub> + 1	V
“L” Output Voltage	V <sub>OL</sub>	TTL I <sub>OL</sub> = 2.1 mA		0.4	V
		CMOS I <sub>OL</sub> = 100 μA		0.1	V
“H” Output Voltage	V <sub>OH</sub>	TTL I <sub>OH</sub> = -400 μA	2.4		V
		CMOS I <sub>OH</sub> = -100 μA	V <sub>CC</sub> <sup>-0.5</sup>		V
Input Leakage Current	I <sub>LI</sub>	V <sub>in</sub> = 5.5 V		10	μA
Output Leakage Current	I <sub>LO</sub>	V <sub>out</sub> = 5.5 V CS = 0		10	μA

AC CHARACTERISTICS

Parameter	Description	Test Condition	Min	Typ	Max	Units
t <sub>CSS</sub>	CS Setup Time		0.2			μs
t <sub>CSH</sub>	CS Hold Time		0			μs
t <sub>DIS</sub>	DI Setup Time		0.4			μs
t <sub>DIH</sub>	DI Hold Time		0.4			μs
t <sub>PD1</sub>	Output Delay to 1	CL = 100pF V <sub>OL</sub> = 0.8V, V <sub>OH</sub> = 2.0 V <sub>IL</sub> = 0.45V, V <sub>IH</sub> = 2.4			2	μs
t <sub>PD0</sub>	Output Delay to 0				2	μs
t <sub>HZ</sub>	Output Delay to HiZ				0.4	μs
t <sub>EW</sub>	Erase / Write Pulse Width				10	ms
t <sub>CSMIN</sub>	Min CS Low Time		1			μs
t <sub>SKHI</sub>	Min SK High Time		1			μs
t <sub>SKLOW</sub>	Min SK Low Time		1			μs
t <sub>SV</sub>	Output Delay to Status Valid	C <sub>L</sub> = 100 pF			1	μs
SK <sub>MAX</sub>	Maximum Frequency		0		250	kHz



Synchronous Timings

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DEVICE OPERATION

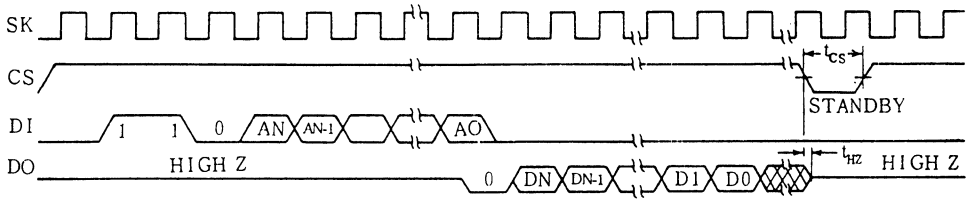
The MSM 16811 has 7 instructions that allow it to read, erase, or write. Each instruction consists of a start bit logical '1', an opcode field (2 bits or 4 bits) and an address field (6 or 7 bits).

The DO pin is a multiplexed pin. It is used as Data Out during the Read mode. It can also be used as a Ready Busy status indicator in programming mode. In all the other modes DO is tri-stated.

During power-up, all modes of operation are disabled and the device comes up in a program disabled state. An EWEN instruction has to be issued before starting to program.

At power-down, when V<sub>CC</sub> falls below a level of approximately 3V, the data protection circuitry inhibits all modes of operation and an EWDS instruction is executed internally.

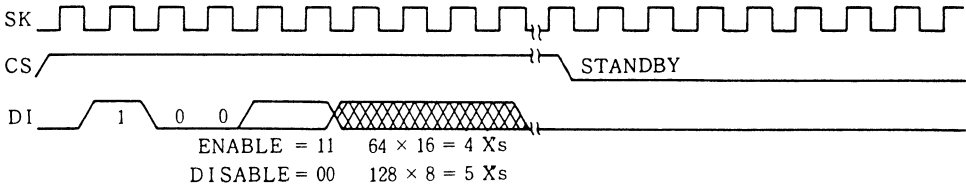
READ MODE



Organization	A <sub>N</sub>	D <sub>N</sub>
128 x 8	A <sub>6</sub>	D <sub>7</sub>
64 x 16	A <sub>5</sub>	D <sub>15</sub>

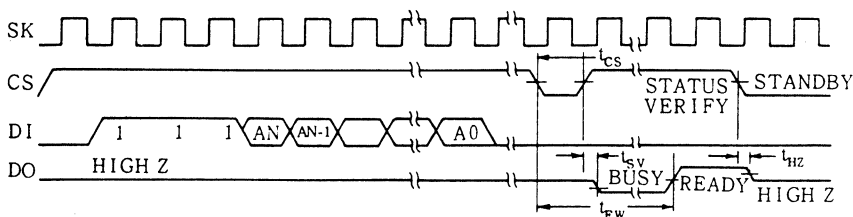
The READ instruction reads the contents of the addressed register. It outputs data serially on the DO pin. After the instruction is decoded, a dummy bit (logical "0") precedes the output data string.

ERASE/WRITE ENABLE AND DISABLE



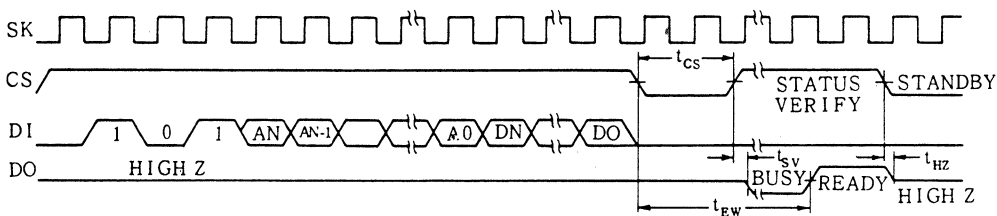
After power-up and before starting any programming instruction the EWEN instruction has to be issued. Once it has been issued, it will remain active until an EWDS instruction takes place. The EWDS instruction is provided to avoid any accidental programming of the part. The READ instruction is independent from the EWEN and EWDS instructions.

ERASE MODE



After an ERASE instruction has been shifted in. CS is dropped low. This will set the beginning of the self timed erase sequence. If CS is then brought high (after observing  $t_{CS}$  spec) the DO pin will act as a status indicator. It will remain low as long as the chip is programming. It will go high after all the bits of the addressed register have been set to a logical '1'.

WRITE MODE

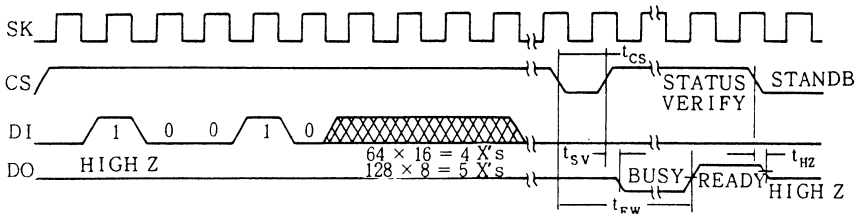


After a WRITE instruction has been shifted in with the corresponding 8 bits or 16 bits of data, CS is dropped low. This will set the beginning of the self timed programming sequence. If CS is brought high during the programming time (after observing the  $t_{CS}$  specification), the DO pin will act as a status indicator — it will remain low as long as the chip is programming. It will go high after all the bits of the addressed register have been set to their proper value. With the MSM16811 it is NOT necessary to erase a memory location before the WRITE instruction.

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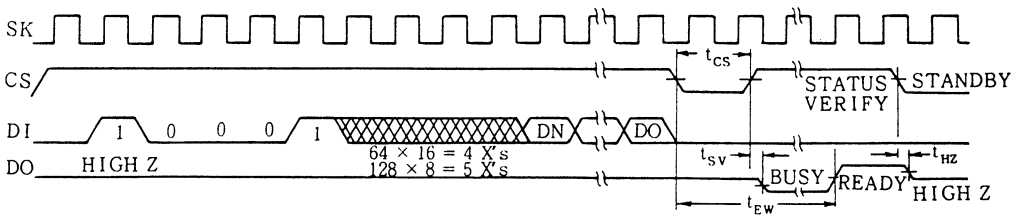
Configuration	A <sub>N</sub>	D <sub>N</sub>
128 x 8	A <sub>6</sub>	D <sub>7</sub>
64 x 16	A <sub>5</sub>	D <sub>15</sub>

ERASE ALL



This instruction is provided to erase the whole chip. Besides its different opcode, the ERAL instruction is identical to the ERASE instruction.

WRITE ALL



This instruction is provided to write simultaneously all the registers. All the registers must be erased before doing a WRAL operation. Besides its different opcode, the WRAL instruction is identical to the WRITE instruction.